



NANOLITO NETWORK

Zaragossa 26th may 2009

The technical support in a French
 Technology Platform of the **B**asic **T**echnological **R**esearch Network
 The example of LAAS-CNRS



Laboratory for Analysis and Architecture of Systems

Research topics

The people

The structure

Technical means

LAAS : SYSTEMS and APPLICATIONS

- **Kinds of systems**

- Micro and nano systems
- Embedded Systems
- Integrated Systems
- Large Scale distributed Systems
- Biological Systems
- Mobiles Systems
- Autonomous Systems
- Critical Infrastructures

- **Applications**

- Aeronautics
- Space
- Transports
- Energies
- Services
- Health
- Telecommunications
- Environment
- Production
- Military

LAAS : THE PEOPLE

Searchers : 534

86 CNRS, 1 INSERM

105 Professors-searchers

9 CNRS hosts

1 detached from industry

7 contractual searchers

6 Associated serachers

44 Post-Phd

273 PHD

2 CNAM (continuous formation)

Technical Staff : 115

87 ITA (CNRS)

5 ITAOS (University/Engineers school)

23 Contractuals

649

At the 1st of January 2009

LAAS : STRUCTURE

| |
|-------|
| ISGE |
| M2D |
| MINC |
| MOST |
| N2IS |
| NBS |
| PHOTO |

**M
I
N
A
S**

Micro and
Nano Systems
A-M. Gué

| |
|--------|
| DISCO |
| MAC |
| MOGISA |
| MRS |

**M
O
C
O
S
Y**

Modelling,
Optimisation and
Control of Systems
L. Travé Massuyès

| |
|---------|
| GEPETTO |
| RAP |
| RIS |

**R
I
A**

Robotics and
Artificial
Intelligence
R. Alami

| |
|-----|
| CDA |
| ISI |
| OLC |
| TSF |

**S
I
N
C**

Critical Information
Systems
J. Arlat

Groups of research

*Thematic
Areas*

Direction

*R. Chatila
J-L. Sanchez*

**General
Secretary**
A. Filipowicz

Technical Services

II
Computing and
instruments

TEAM
Technics and Equipments Applied to Microelectronics

Administrative services:
Financial
Contractual Relations and partnerships
Human ressources
Support Services :
Library-Edition
Information Systems
Logistics Services :
Logistic
Store

Services

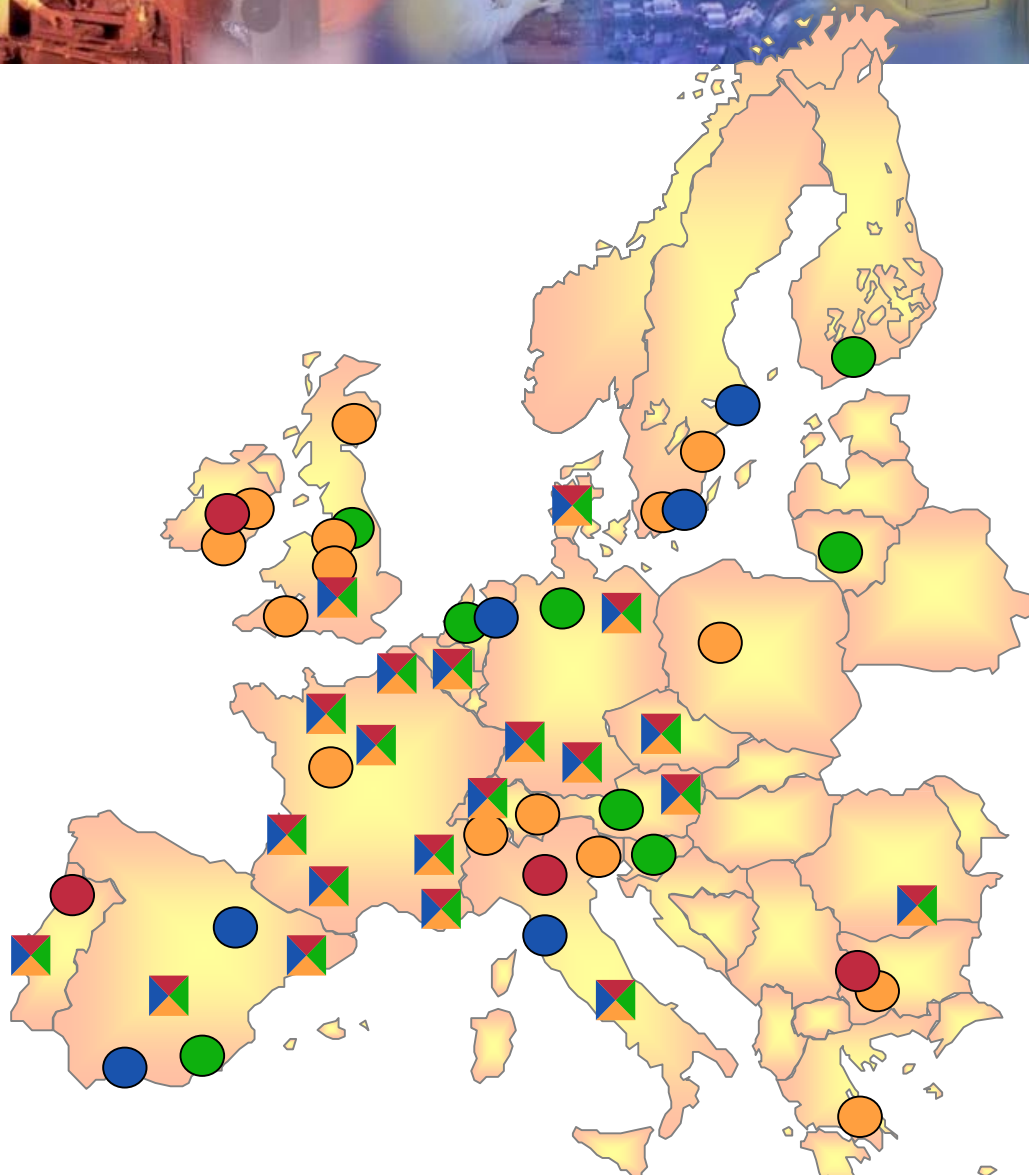
LAAS : TECHNICAL MEANS



- **BTR technological platform** : microelectronics, optoelectronics components, micro and nano systems
- **Characterization platform**: components tests, micro-nano systems: electronic, optical, UHF
- **Robotic platform**: a tenth of robots
- **Micro systems conception platform**
 - Methodologies
 - Industrials and Research softwares
- **“Network” platform**
 - Experimental validation on complexes architectures
 - Metrologies, modelling, security
- **“Embedded Systems” platform**
 - Software Integrations, captors, actuators, dynamic modelling of “embedding” systems, Conception Industrials and Research softwares

CPER
2007-2013
« ADREAM »

EUROPEAN COLLABORATIONS



- MINAS
- RIA
- MOCOSY
- SINC
- ◻ multiple

SUPPORT TO MICRO AND NANO SYSTEMS DEVELOPMENTS

The technology platform

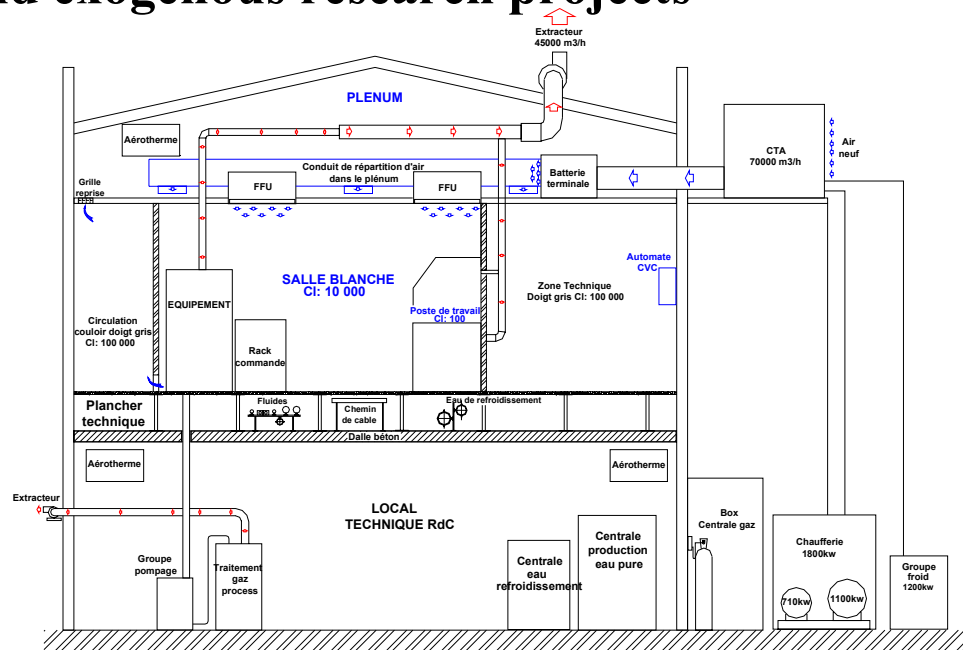
The technical staff

THE TECHNOLOGY PLATFORM

Facilities

- Adaptive structure
 - 4 levels architecture
- 1500 m² clean room
 - Specialized areas
- From class 10 000 up to class 100
 - Upgradeable (Filter Fan Units)
- Control of running costs
 - 1.5 M€ in 2008

Support endogenous and exogenous research projects

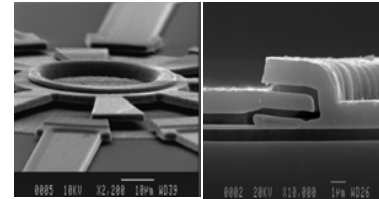


Investments

- Since 2003 : 16.5 M€ (half from LAAS own resources)
- Building : 2.4 M€ (CPER) + 3.9 M€ (RTB)
- Equipment : 10.2 M€

THE TECHNOLOGY PLATFORM

- 25 M€ equipment total value
- Equipments policy
 - Manuals / Semiautomatic /Automatic equipments
- Si and III-V technologies
 - (Diamond, GaN, polymers,...)
- 4" Si wafers (upgradeable to 6 ")
- Developments in substitution technologies



To Characterization

Packaging

Ion implantation

Electrochemical deposition

Plasma Etching

Metallization

M.B.E.

Wet Etching

Infrastructure and support

Chemistry

Thin films deposition

Electronic lithography

Optical photolithography

From Mask fabrication



EQUIPMENTS POLICY

Complementary equipments for an adapted support

Flexibility

(adaptability to projects)

vs.

Specificity

(axes)

Development

(parameters understanding, prototyping)

vs.

Repeatability

(Formalization, valorization)

Constant investments (more then 3 M€ in 2007)

- BTR Conventions
- Institutional (CNRS, Region,..)
- Collaborations et partnerships (ANR, Europe, .., common, affiliates club, ...)
- Own resources (COMÉQ, general interest of the laboratory)

A planning taking into account

The necessary youth of some equipments
 “Alternative” technologies

Technical developments
 Technical prospective

MATERIAL ELABORATION

- **Molecular Beam Epitaxy**

(GaAs based)

- Photonics structures
- Surface nano structurations



- **Furnaces**

- Oxidation Si, III-V alloys (Al based)
- SiO_xN_y
- Si_3N_4
- Sipoly
- LPCVD



- **Chemistry**

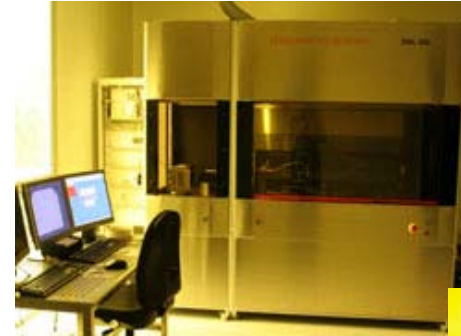
- Sol gel, polymers, ...
- Synthesis Developments



MATERIAL « SHAPING »

• Lithography

Masks fabrication



1-2 μm Optical photolithography

0.3 - 0.4 μm Projection lithography

Electron Beam Lithography

Nano replication (in 2009)



MATERIAL « SHAPING »

• Etching

DRIE

(Si 4'', 6'' and glass)

ICP

(Si and derivate, III-V, Polymers, metals)

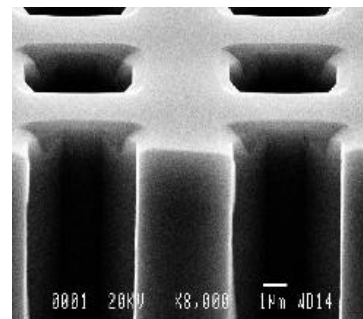
Stripping

Chemistry

(metals, resists,..)

KOH, TMAH

Vapor phase (in 2009)



MATERIAL « SHAPING »

- **Deposition**

PVD

Electrochemistry

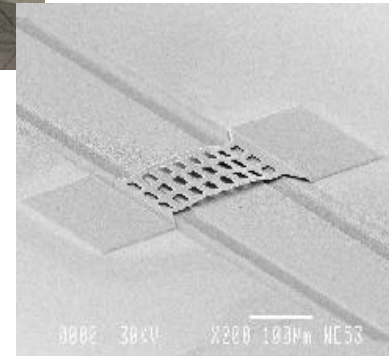
(Au, Cu, magnetic alloy)

PECVD

(SiO₂, Si₃N₄)

LPCVD

SiO_xN_y, Si₃N₄, Si poly



MATERIAL « SHAPING »

- **Packaging**

Dicing



Pick and place

(manual, semi-auto)



Connexion

(wires, flip chip)



WLP

(CMP, grinding, Wafer bonding)



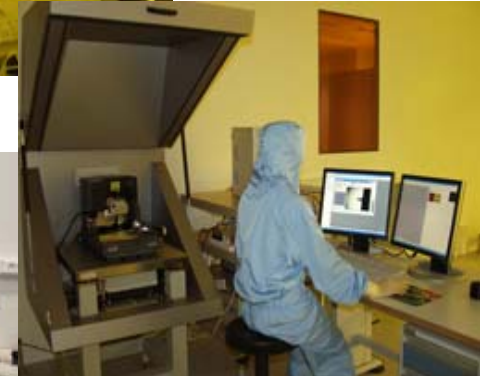
MATERIAL TREATMENT

- **Thermal**
(Annealing, RTA, diffusion, redistribution)
- **For surface preparation**
(plasma, chemical)
- **Ion Implantation**



CHARACTERIZATION

- **2 SEM**
(X surface analysis, variable pressure)
- **AFM**
- **Optical Microscopy**
(2D, 3D)
- **Profilometers**
- **Ellipsometers**
- **4 probes**



A CONSTANT EVOLUTION

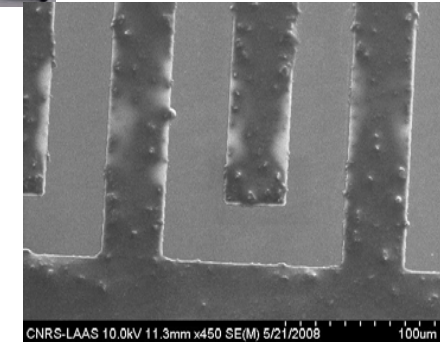
- **ALTERNATIVES TECHNOLOGIES**

- Ink Jet
- Screen printing
- Nano replication
 - UV NIL



- **UP TO COME**

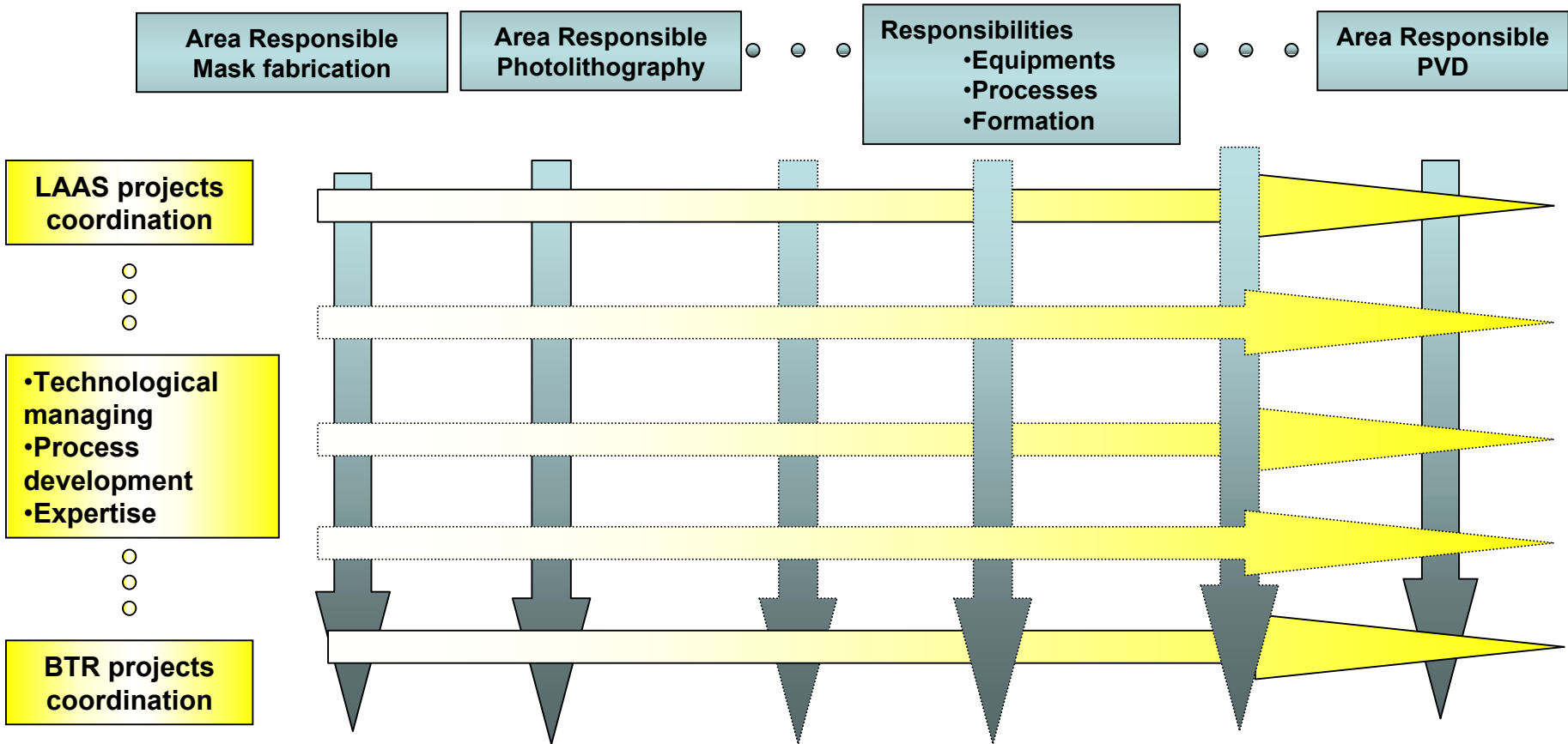
- Low T° PECVD
- 1800° C furnace
- Spray coater
- Vapor phase etching
- Wafer bonding (duplication)
- Nano replication
 - Micro contact printing
 - Hot embossing
- AVD (OMCVD or ALD?)



THE STAFF

Technics and Equipments Applied to Microelectronics

30 Engineers, Engineer Assistants and Technicians directly under the authority of the director



TEAM : IDENTIFIED COMPETANCIES

Elaboration, shaping, treatment et characterization of materials

| | | | | | | | | | | | | | |
|-------------|--|--|--|--|--|--|--|--|--|--|--|--|--|
| Elaboration | | | | | | | | | | | | | |
| shaping, | | | | | | | | | | | | | |
| treatment | | | | | | | | | | | | | |

In technical areas, open to all projects

| Infrastructure and Support | Mask Fabrication | Photo-lithography | Electron beam lithography | Molecular Beam Epitaxy | Chemistry | Thermal Treatments | PVD | Electro-chemistry - Si wet etching | Plasma etching | Packaging | Ion Implantation | Ink Jet | Nano replication |
|----------------------------|---------------------------------------|---------------------------|---------------------------|--------------------------|-----------------------------|--------------------------|-------------------------|------------------------------------|---|---------------------------------------|----------------------------------|---------------------------|---|
| Fadel Paul IE2 | Calmon Pierre François. IR2 | Conédéra Véronique IR1 | Carcenac Franck IR2 | Arnoult Alexandre IR2 | Doucet Jean Baptiste IE2 | Rousset Bernard IR1 | Salvagnac Ludovic AI | Dilhan Monique IR2 | Dubreuil Pascal IR2 | Granier Hugues IR2 | Imbernon Eric IR2 | Fabre Norbert IRHC | Daran Emmanuelle IR1 |
| Benoit Monique TCE | Aouba ¹ Stéphane IR2 | Mazenq Laurent AI | Daran Emmanuelle IR1 | Lacoste Guy IE2 | Mesnilgrete Fabien AI | Bouscayrol Laurent AI | Pinaud Sébastien AI | Bourrier David AI | Belharet ¹ Djaffar IR2 | Do Conto Thierry TCE | Marrot Jean Christophe TCE | Conédéra Véronique IR1 | Jalabert ² Laurent IR2 |
| Maiorano Antoine TCN | | Mesnilgrete Fabien AI | | | | | | | Jalabert ² Laurent IR2 | Colin René AJTP2 | | Mesnilgrete Fabien AI | |
| Fourcade Christine TCN | | | | | | | | | | Charlot ¹ Samuel IE2 | | | |

1 : Contractual

2 : Detached at LIMMS in Tokyo

TEAM : PRECISE MISSIONS

- **Responsibility for the equipment**
 - Implementation, safety
 - Maintenance, evolutions
 - Appraises and technical survey

- **Responsibility for operation of the clean room infrastructure**
 - Adaptation, development and maintenance
 - Management of the tasks of general interest (management of process gas, safety, provisioning, etc...)

- **Support to MINAS research projects**
 - Development of basic and specific processes (70 projects in 2009)
 - Coordination, participation in the technological realizations
 - Assistance, technical management of the PHD

- **Hosting and support of exogenous projects (nearly 50 in 2008) (member of network RTB)**
 - Expertise/administration of the requests
 - Interactions with the applicants
 - Hosting /formation of external people
 - Realization of the projects

- **Formation, capitalization, valorization and transfer**



THE PROJECTS

From the lab

From the BTR network

Origins
 The management
 Some examples

INTERNAL PROJECTS FROM MINAS

Bridging the Gap between Chip and Application

Functional integration

Interaction with user & environment
Non-digital content
Hetero Integration
Lots of processes
SiP Integration

More than Moore

Lab on chip

Nano technology
Microfluidic
3D Packaging

MOEMS

Hetero structures for laser emission
Photonic crystal on silicon

Sensors actuators

Materials for detection and actuation (Piézo...)

RF MEMS

Silicon membrane
BCB technology

Passives

Magnetic Dielectric

HV Power

Isolation

RF ICs

Baseline CMOS

Embedded, Memory

More Moore

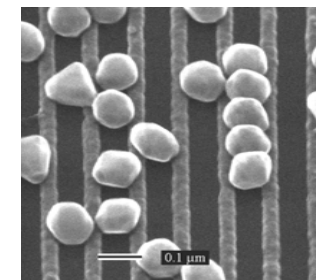
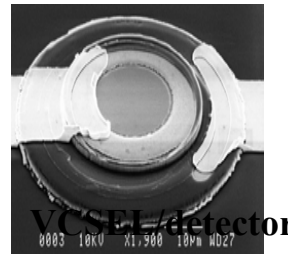
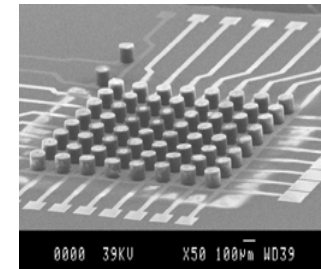
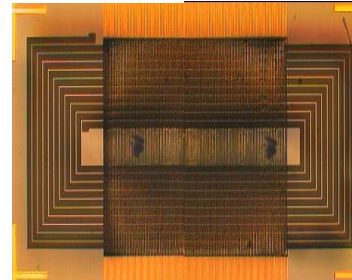
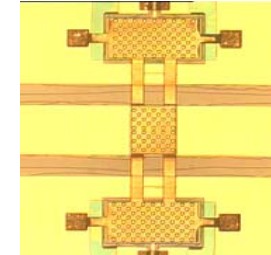
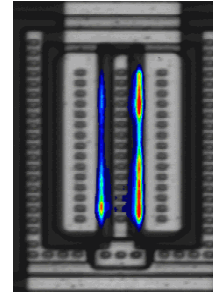
Signal Processing
Digital content
Complex Design (SoC)
Complex technology
Lots of software

Size reduction

INTERNAL PROJECTS : RESEARCH GROUPS

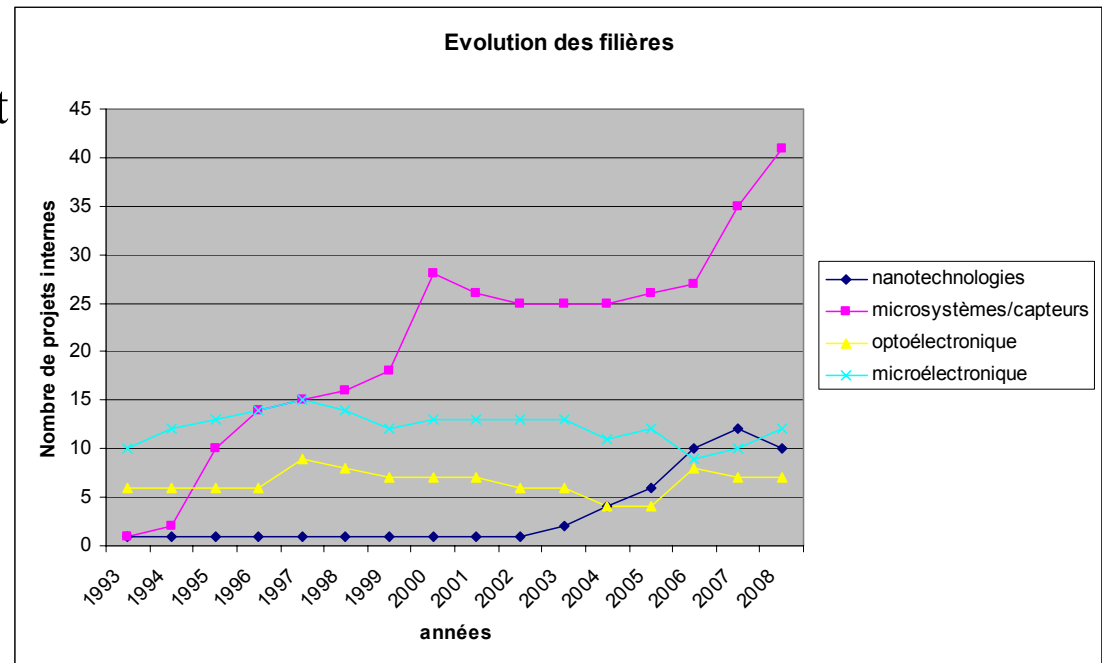
MINAS: Micro Nano Systems

- ISGE: Power Integration and management Systems
- M2D: Detection Micro devices and Microsystems
- MINC: Micro nano systems for communications
- N2IS: Nano Engineering and Systems Integration
- MOST: Microwaves and optronics for communication systems
- NBS: Nano biosystems
- PHOTO: Photonics



INTERNAL PROJECTS : MANAGEMENT

- COMTEAM
 - Under the presidency of the director
 - Analyze the projects
 - Activities of general interest
 - Calculation of IT needed implications
 - Activities analyze
 - Analyze BTR actions
 - Helps to define :
 - Lacks of IT
 - Needed equipments
 - Inventories and evolution of projects



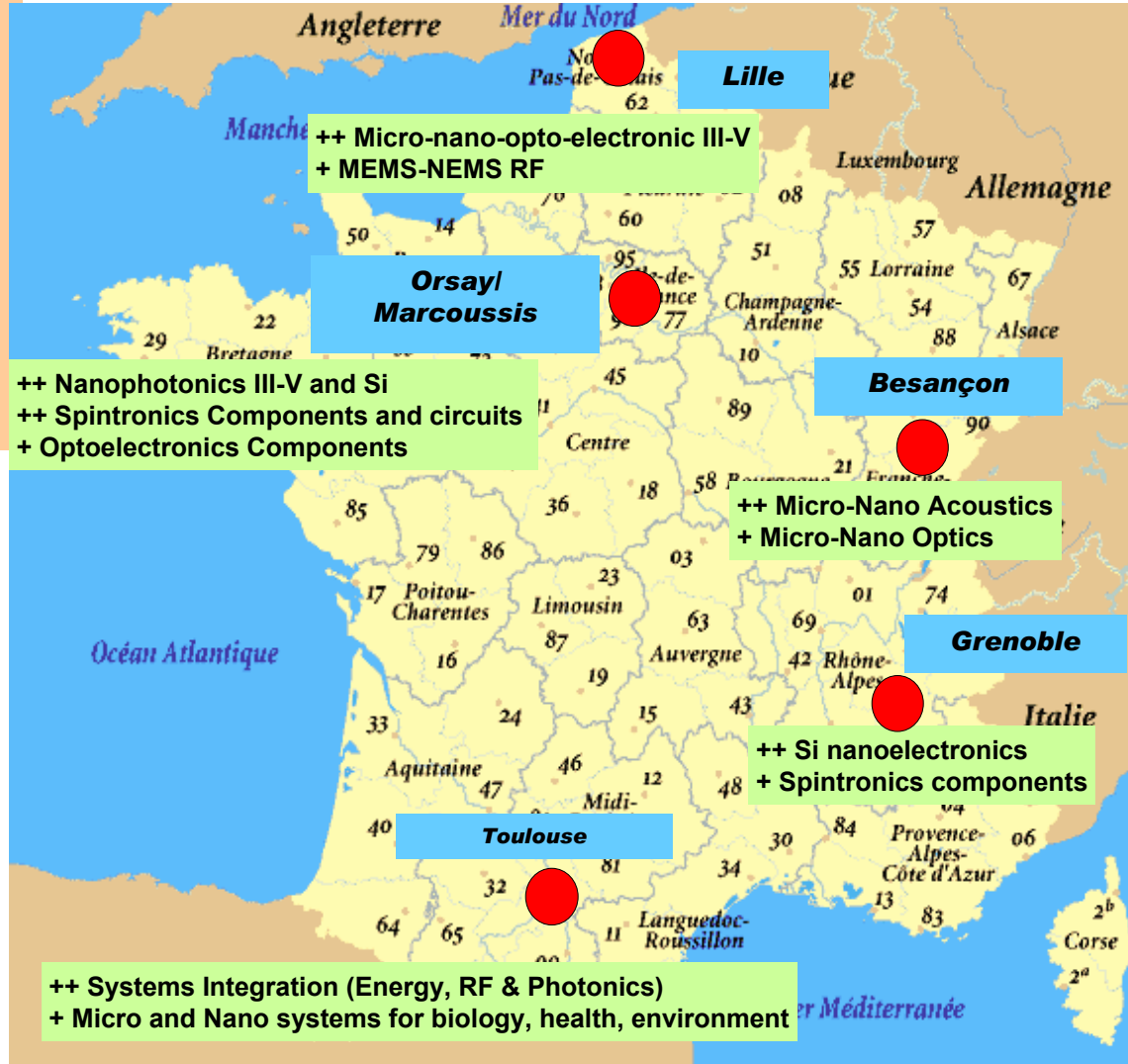
EXTERNAL PROJECTS : BTR NETWORK : GENESIS AND OBJECTIVES

- **2003 Dedicated program decided by Ministry of Research:**
"A national network of large technological facilities and Basic Technological Research (BTR) in micro and nanotechnologies "
- 100 M€ National program leaded by CEA and CNRS (Renatech GIS)
- **3 different complementary objectives.**
- **To enhance the level of equipment**
 - A few selected clean rooms in France (so-called large technological facilities)
 - A network, open to the need of the academic scientific community and of industrial research projects.
- **To focus a scientific program on few priority areas**
 - Micro- and Nanoelectronics, Nanosciences and Nanotechnologies, Photonics and optoelectronics, Micro Nano and Biosystems and Heterogeneous integration of technologies
- **To enhance the use of joint vision and exploitation of research results**
 - Setting up a unit, in charge of the scientific survey in the field of Micro and Nanotechnologies (OMNT).
 - Promoting patenting and researcher mobility.

EXTERNAL PROJECTS BTR FACILITIES

• **6 CNRS laboratories (GIS RENATECH)**

- IEMN (Lille),
- LAAS (Toulouse),
- FEMTO (Besançon),
- FMNT-INAC (Grenoble),
- LPN (Marcoussis)
- IEF (Orsay)



CEA-LETI (Grenoble)

- ++ Above IC
- ++ Microelectronics
- ++ Photonics
- + Biochips

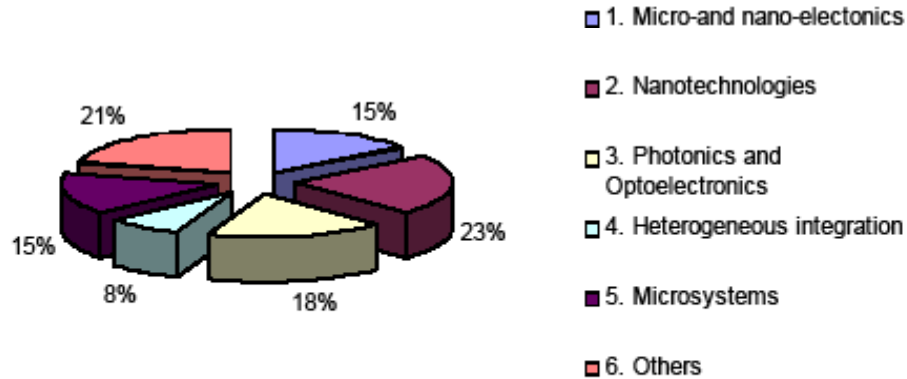
EXTERNAL PROJECTS

BTR NETWORK : FACILITY OPENING TO ACADEMIC AND INDUSTRIAL COMMUNITY

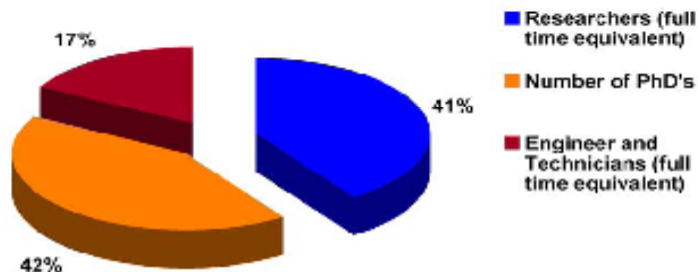
- **For each platform**
 - A team to receive the proposed projects.
 - Technological feasibility and cost evaluation.
 - Agreement for cost supporting to be defined between the proposer and the platform.
 - Training programs for the proposer to participate actively to the execution of the process
- **Common tools**
 - Centralized network administration via the administrative manager
 - A WEB site: www.rtb.cnrs.fr (also limited English version)
 - Definition of external projects and evaluation criteria. “Charte d’accueil”.
 - E-mail alias for project dispatching (rtb-accueil@cnrs-dir.fr).
 - Annual meeting to discuss external project reception.
 - Technical meetings for expertise enhancement.
 - Centralized annual survey of external projects.
 - Satisfaction questionnaire addressed to the external users.
- **Evaluation of the network**
 - Annual report to international experts

EXTERNAL PROJECTS BTR NETWORK : SUMMARY 2008

- 289 external projects performed in the network by the CNRS platforms.



BTR NETWORK : PEOPLE INVOLVED IN TECHNOLOGICAL RESEARCH



| BTR lab | Researchers (full time equivalent) | Number of PhD's | Engineer and Technicians (full time equivalent) |
|--------------|------------------------------------|-----------------|---|
| FEMTO-ST | 32 | 45 | 14 |
| FMNT | 95 ⁽¹⁾ | 100 | 33 |
| IEMN | 60 | 88 | 21 |
| IEF | 34 | 15 | 15 |
| LPN | 41 | 14 | 25 |
| LAAS | 57 | 73 | 25 |
| CNRS-ST2I | | | 1 |
| TOTAL | 319 | 335 | 134 |

⁽¹⁾ The platform is not fully operational. The number is a prediction

BTR NETWORK : SHARING A TECHNICAL EXPERTISE

- **Since 2004 : internal technical work groups on process know-how (resp. leaders: J.L. Lorriaux, IEMN, F. Hamouda, IEF, H. Granier, LAAS)**
 - **LITHOGRAPHY PROCESSES**
 - Electronic lithography, U.V. and nano-printing.
 - **DEPOSITION PROCESSES**
 - Stress measurement, equipments for thin layer characterization, and electrolytic deposit, surface modification by chemical treatment, inkjet printing
 - **ETCHING TECHNIQUES**
 - Ion beam etching systems (FIB, IBE), end point detection systems, assembly techniques.

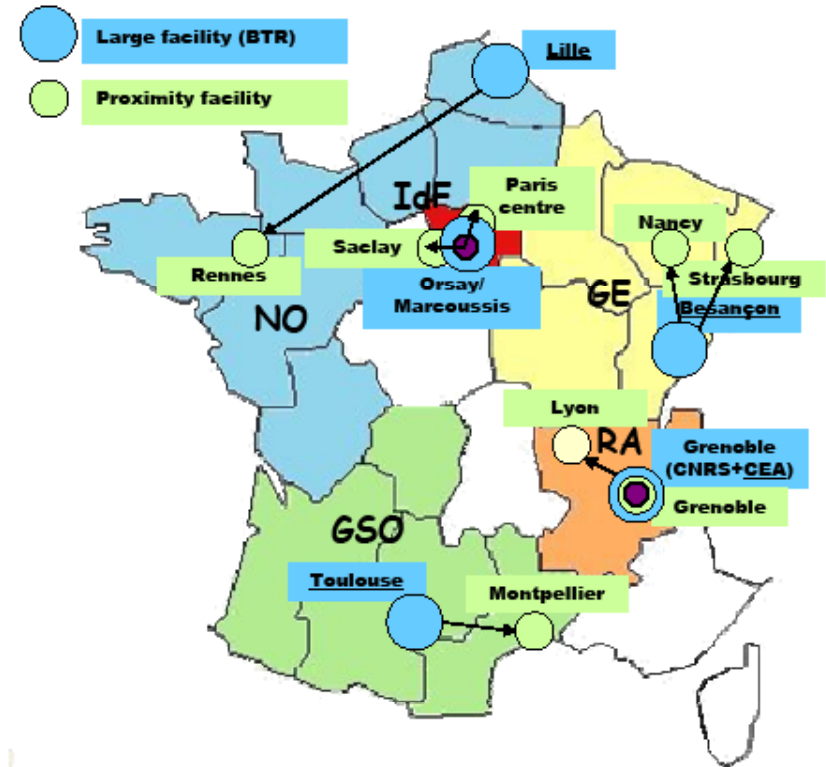
- **This provides a links between engineers and technicians of all the facilities.**
 - Dedicated workshops for the diffusion of information (1/yr)
 - Networking for the purchase of equipments (diffusion of information, grouped purchases)

- **Enhancement of the global competence level and the cooperation between facilities.**
 - Training

BTR NETWORK : THE FUTURE

- The main platforms of Renatech dispatched over the country
 - Each platform is the regional reference with a large coverage of the technologies
- + proximity platforms
 - With specialists in well defined fields
- Double coordination
 - Regional : main and proximity platform associated
 - National : CEA-CNRS

RENATECH 2010-2014

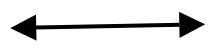


EXTERNAL PROJECTS THE LAAS PROCEDURE

External proposer

plateformertb@laas.fr

Administrative
Technical feasibility
analysis
Cost evaluation



Contacts with other BTR facilities

Host structure : 8IT from TEAM

For each project identification in the service of a coordinator

Support
Developments

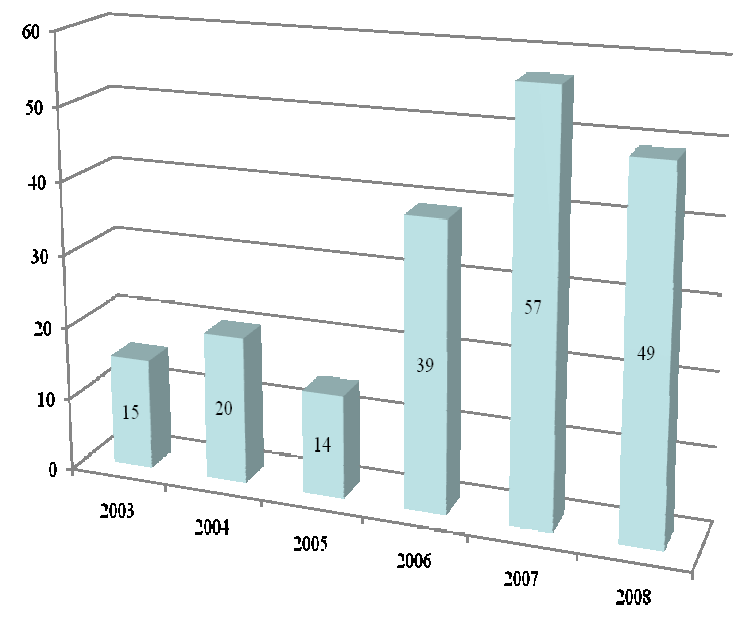
Developments in the scientific
axis of the laboratory

Scientific collaboration

Realization

Internal
and/or
Participation of the proposer

Sending of the components
Cost- Valorization

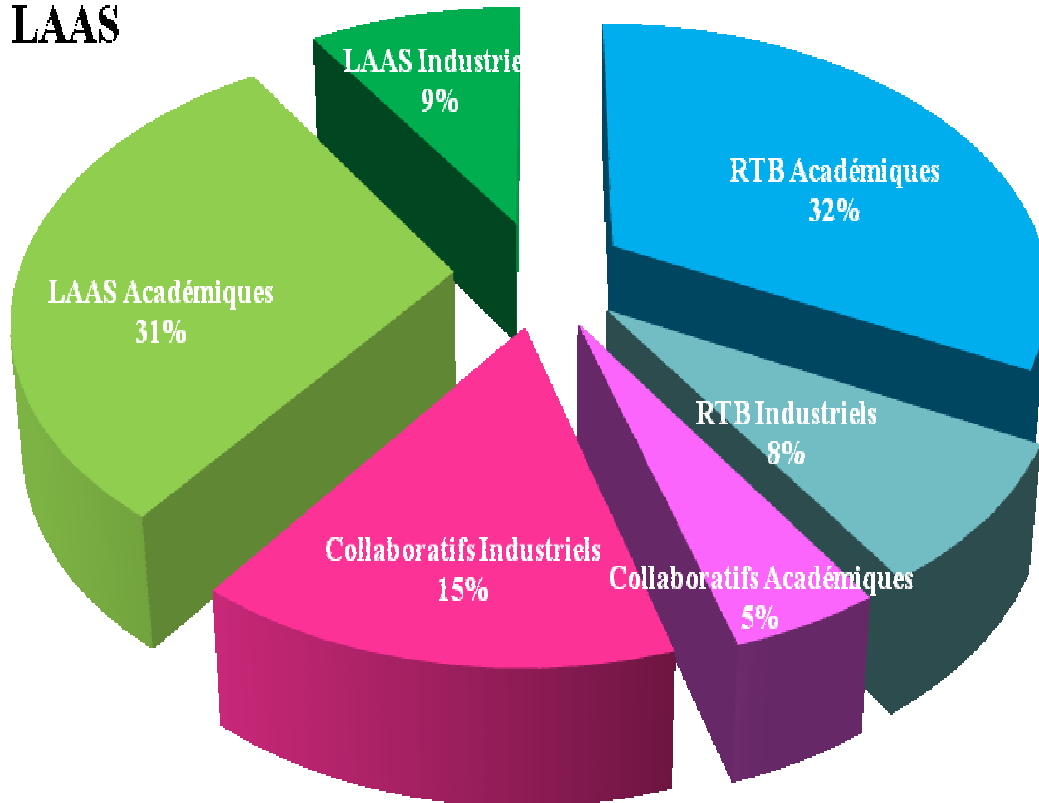


Pure exogenous projects evolution

THE PROJECTS THEIR ORIGIN

- RTB Académiques
- RTB Industriels
- Collaboratifs Académiques
- Collaboratifs Industriels
- LAAS Académiques
- LAAS Industriels

LAAS



RTB

Collaboratifs

Technological families

Biology, health

- Micro/nanofluidic
- Detection
- Nanobiosystems

Basic steps
+
Specific steps

MEMs/NEMs RF

- Microfabrication
- Nanotechnologies
- Above IC

Basic steps
+
Specific steps

Photonic

- Optical sources
- Integrated functions

Basic steps
+
Specific steps

Energy

- Conversion
- Harvesting, Storage

Basic steps
+
Specific steps

Technologies for N/MEMS



Micro an nano systems: biology, health, environment

Micro nanofluidics

Multilevel polymer technology

Surface nano-engineering

- Grafting technologies: silanes UV photografting
- Switchable surfaces

Actuation of fluids and molecules :

- Actuators: Microarray of individually addressable ejectors, Pyrotechnic valves, Flow monitoring using stimuli-responsive SAMs
- Flow engineering using active molecular layers
- Magnetic actuation
- Thermal engineering

Nanofluidics :

- Di phasic nanofluidics for optics
- DNA combing for replication study

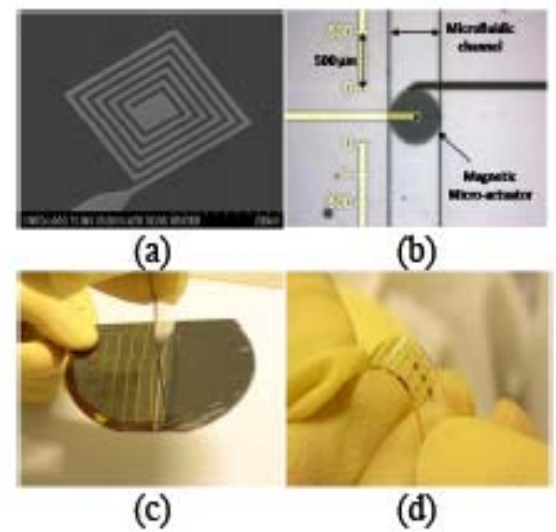
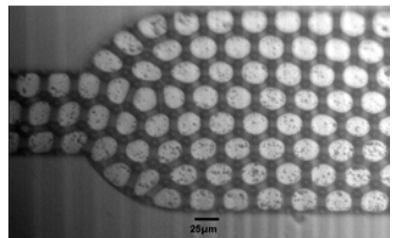
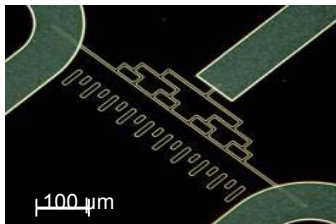


Figure 2 Photographs of the final flexible microsystem. (a) A square magnetic micro-actuator with 5 turns; (b) A spiral micro-inductor embedded in micro-channel. (c) The final step to the technological process: releasing from silicon.

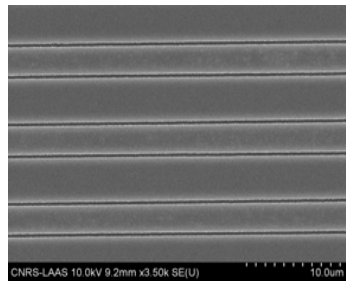
Diect imaging of DNA macromolecules sterched in nnochannels



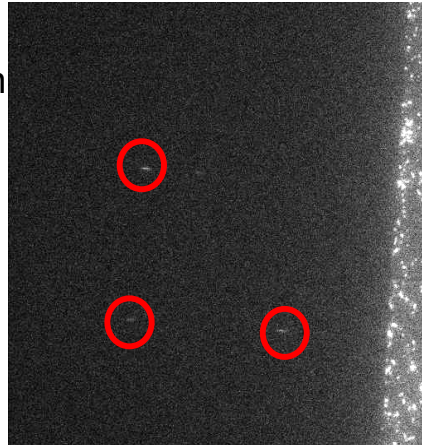
fraction volumique elevee, géométrie en T bull



100 μm



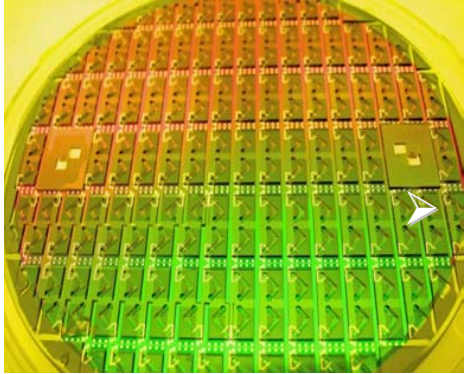
CNRS-LAAS 10.0kV 9.2mm x3.50k SE(U) 10.0um



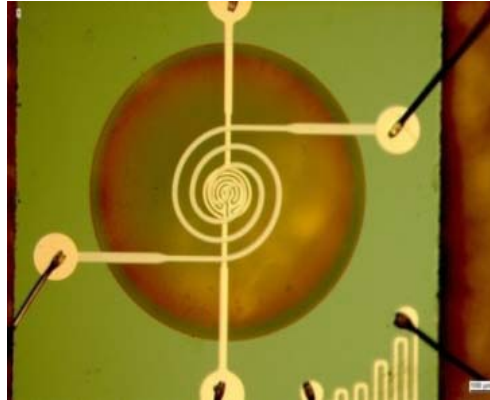
Micro an nano systems: biology, health, environment

Détection

Detection



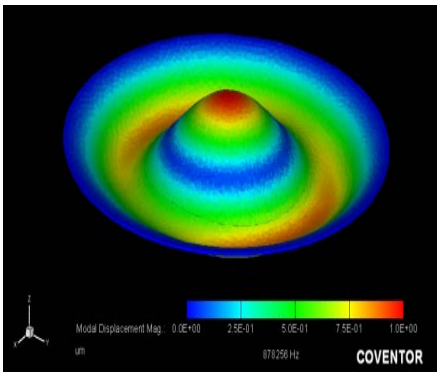
ChemFET



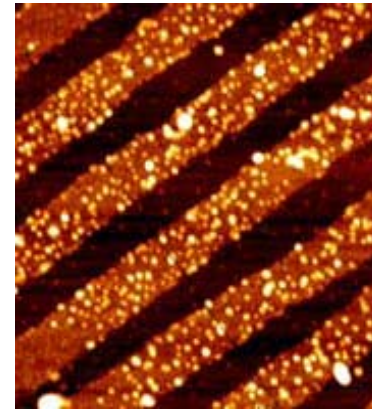
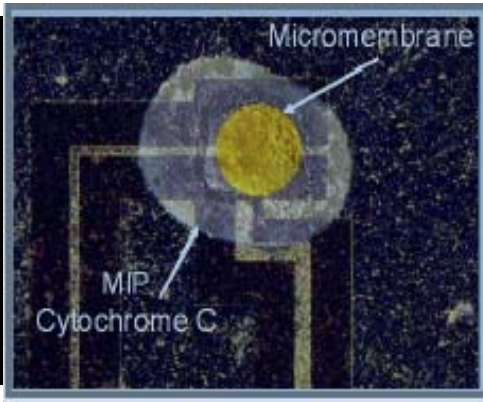
Gaz microsensor



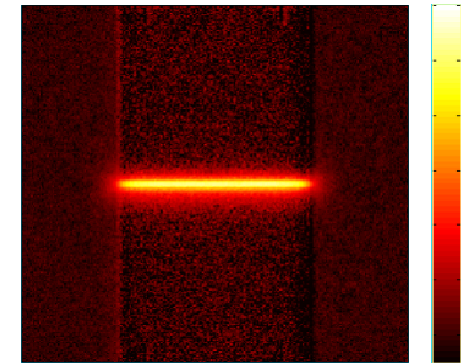
Pressure microsensor



Electromechanic Transduction
(piezoelectric)



Optical transduction
(diffraction)



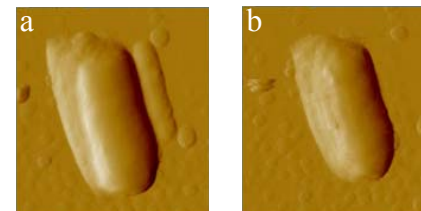
Electro-thermal transduction
(silicon nanowire)

NanoBioSystems

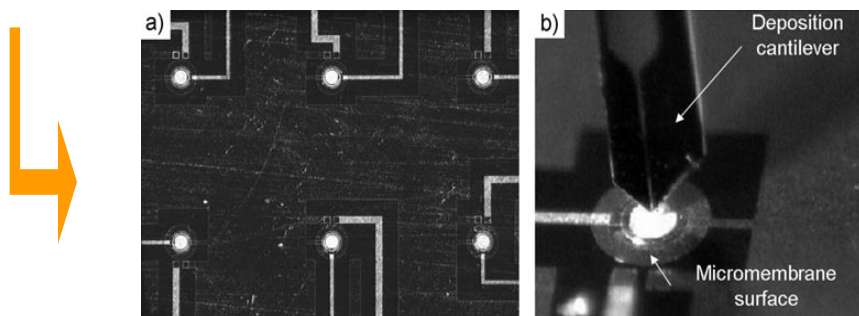
Nanobiosystems' road-map is « DNA-like » double-stranded:

- BIOLOGY-related issues using NANOSYSTEMS
- NANOSYSTEMS-related issues being inspired by BIOLOGY.

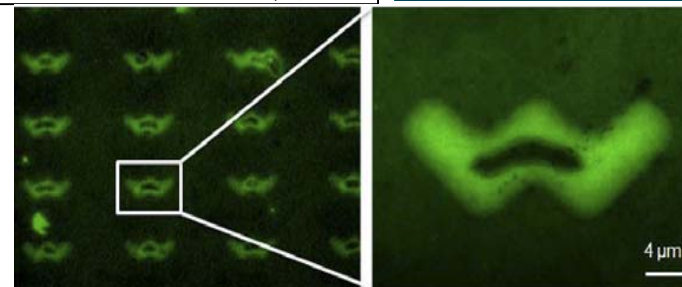
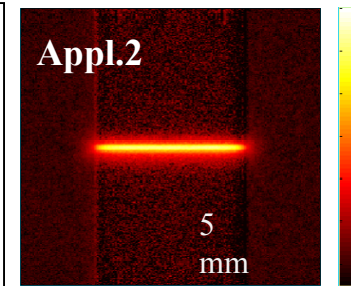
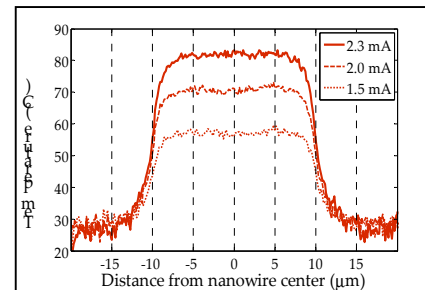
- Nanowires for highly resolute thermometry
- Bioplume: submicron-scale liquid-phase deposition of various materials
- DifraChip: using nanoscale patterning for label-free detection (limit of detection : 100pM)
- Exploring living cells at the nanoscale (yeast, bacteria, fibroblast)



Images of a) a matrix of piezoelectric micromembranes with a global radius of 100 μm and b) a cantilever loaded with MIP precursor solution during deposition onto a micromembrane



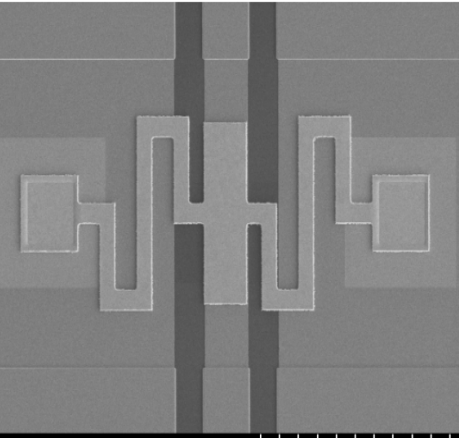
Biotinylated bacteria deposition on a microstructured surface with epoxide-streptavidin functionalized patterns



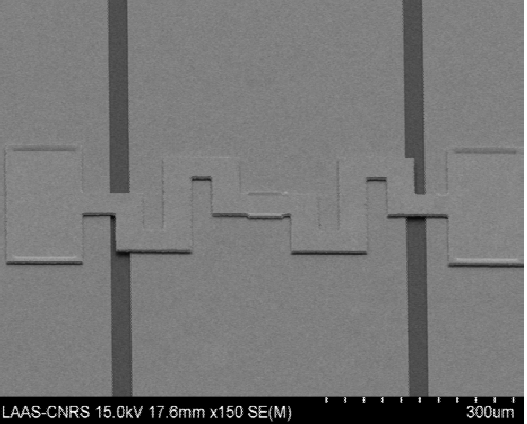
RF MEMS/NEMS

Bulk Silicon Micromachining

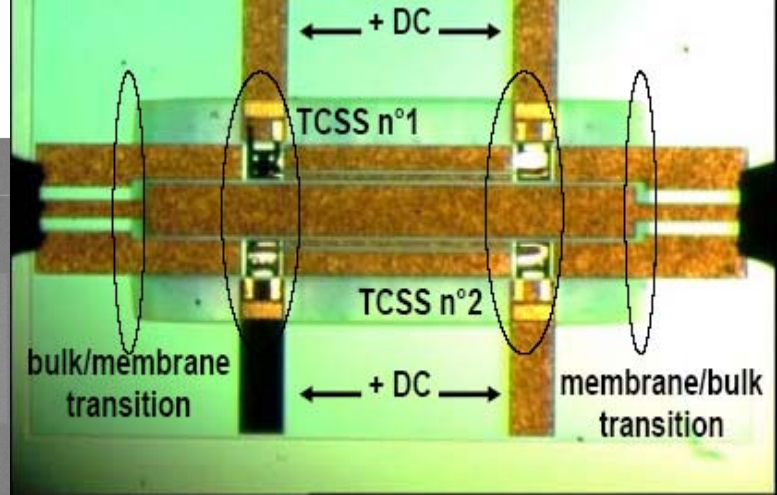
capacitive switch



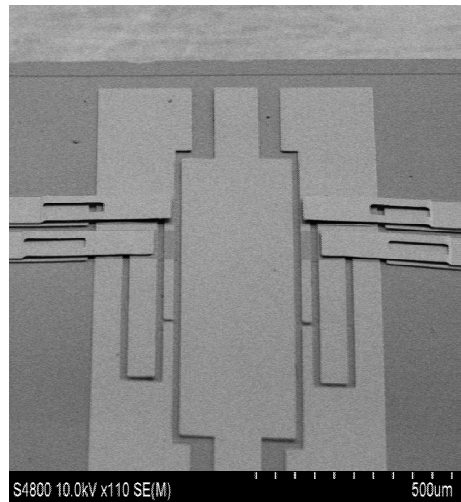
CNRS-LAAS 20.0kV 9.8mm x130 SE(M) 400µm



LAAS-CNRS 15.0kV 17.6mm x150 SE(M) 300µm

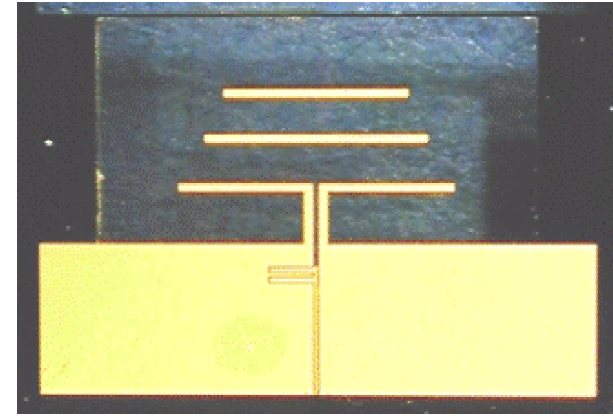


60 GHz Suspended filter

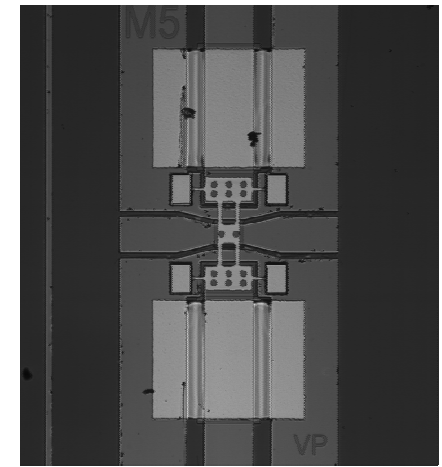


tunable filter @60 GHz

S4800 10.0kV x110 SE(M) 500µm

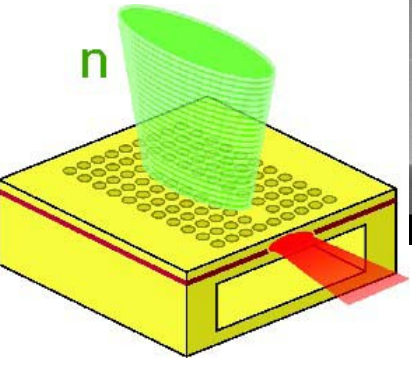


77 GHz suspended yagi antenna

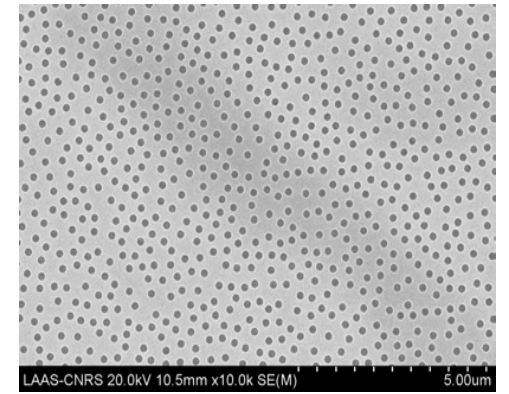
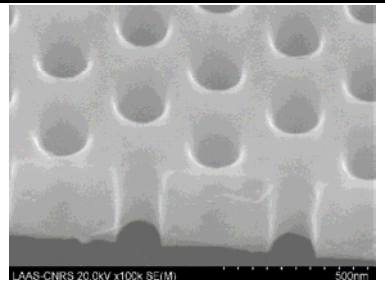
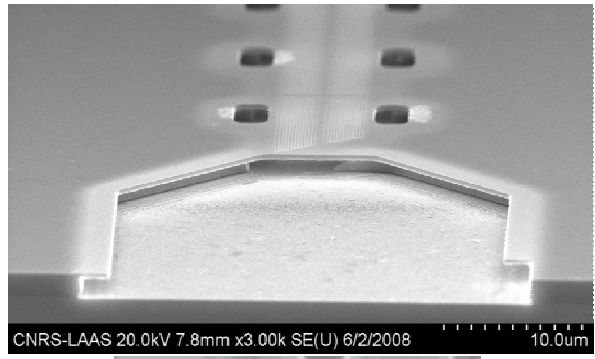


Tunable MEMS 10 GHz to 94 GHz

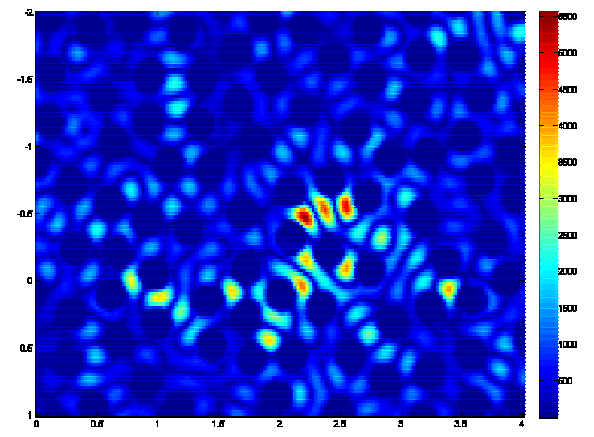
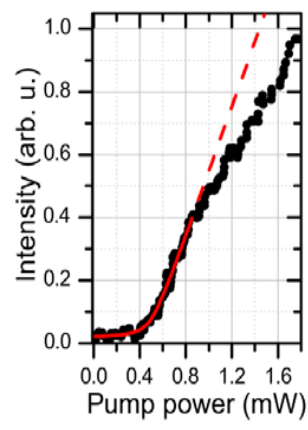
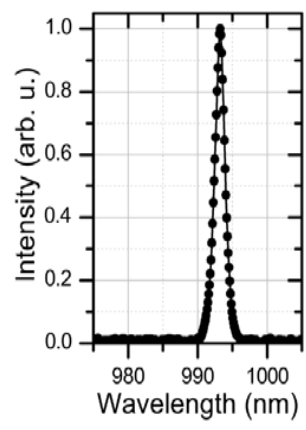
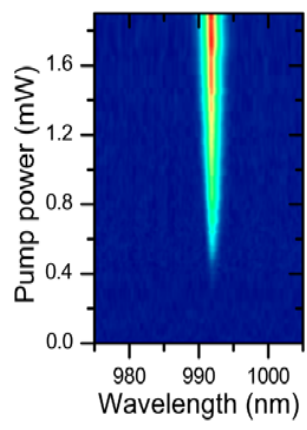
Photonic Optical Sources



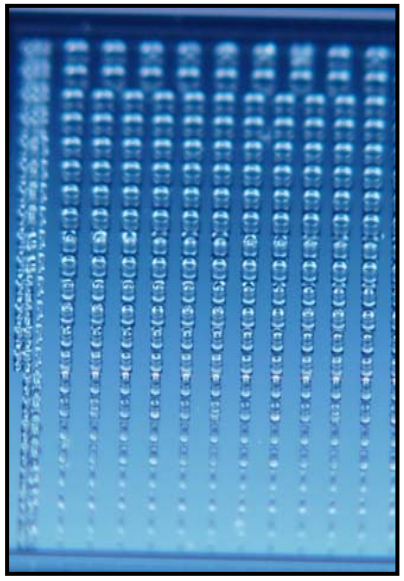
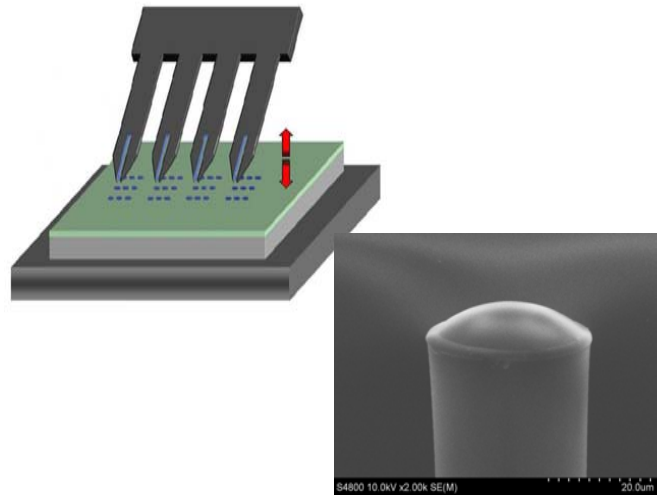
Cristal photonique laser



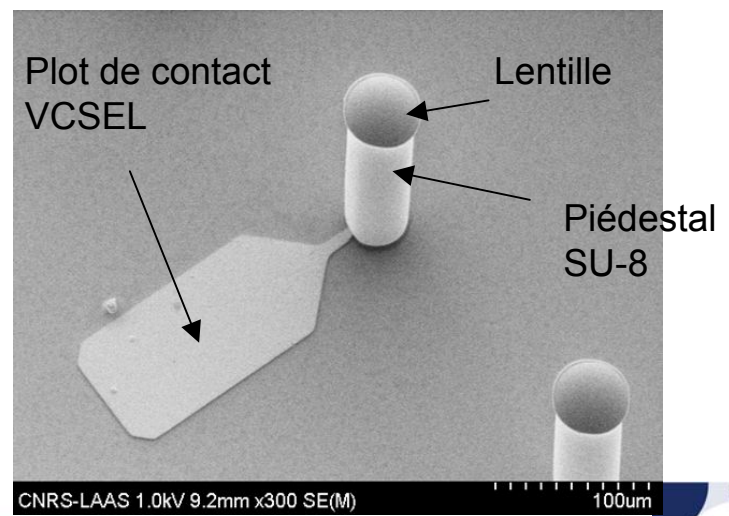
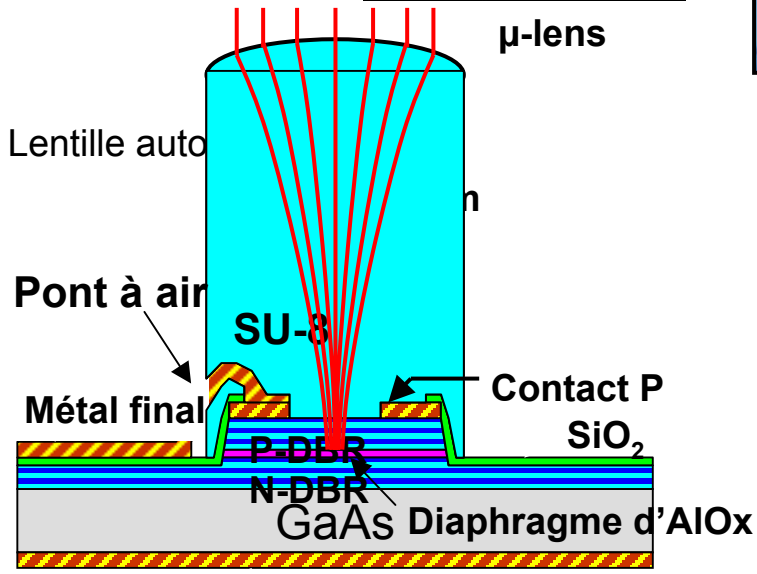
(In)GaAs/AlGaAs membrane



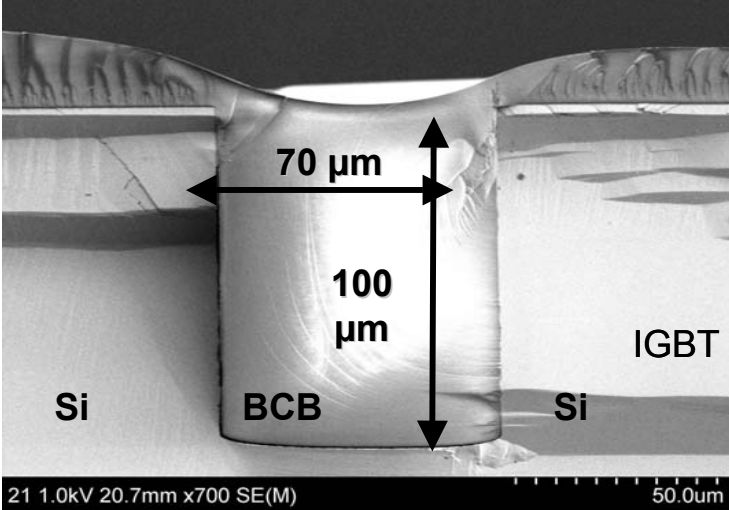
Photonic Integrated optics



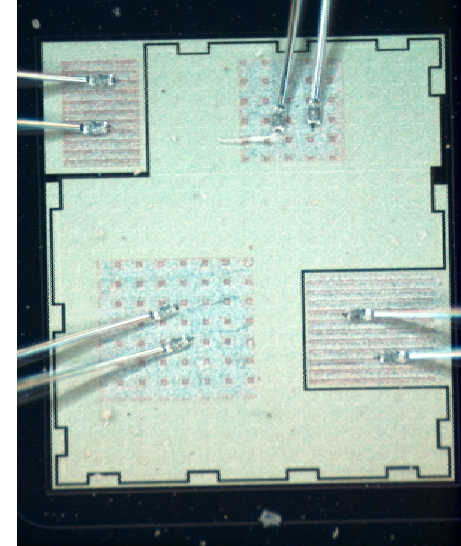
Integrated VCSELs



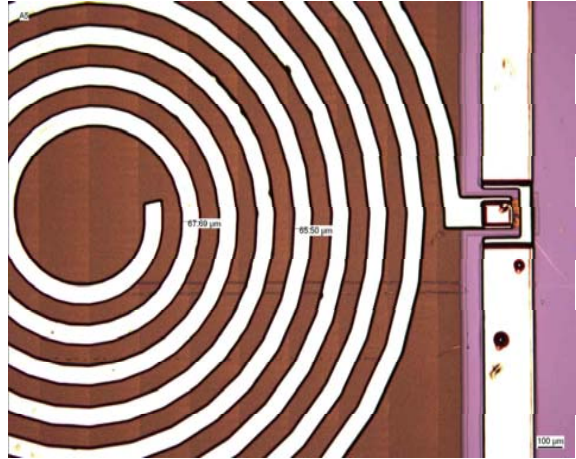
Energy Conversion



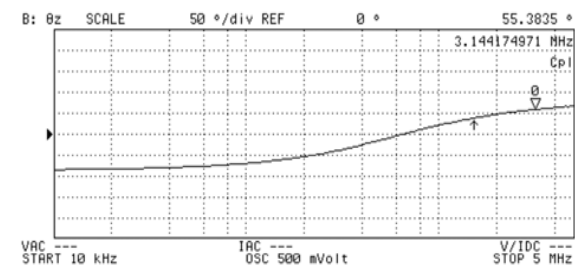
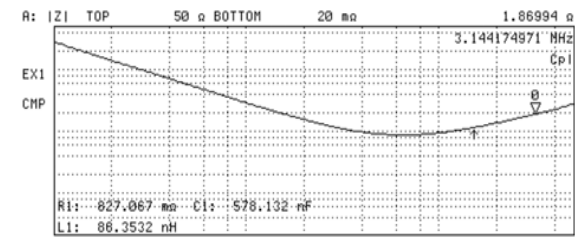
Superjonction Power MOSFET



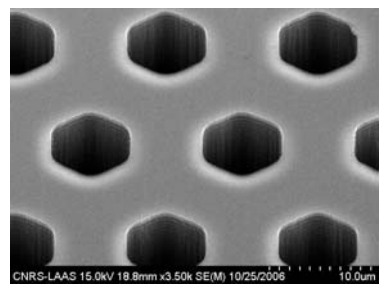
IGBT low losses



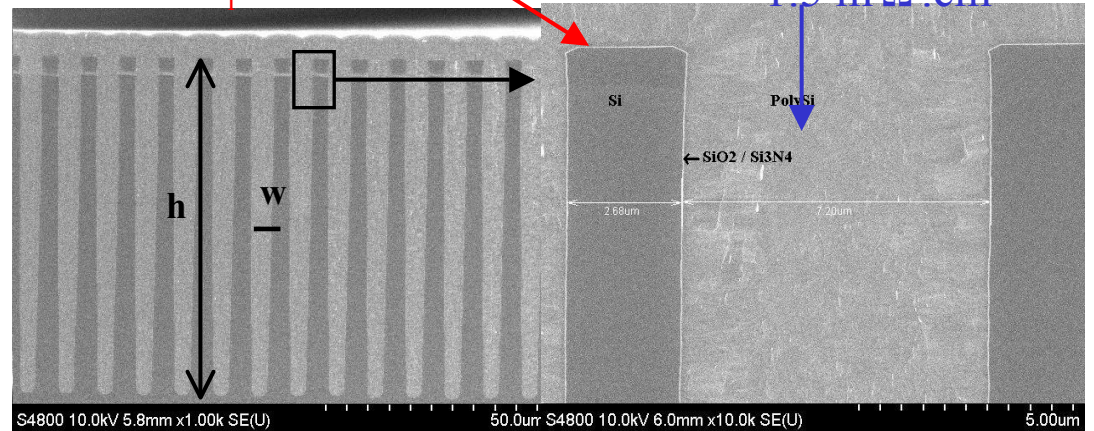
LC filter



Energy 3D Capacitors



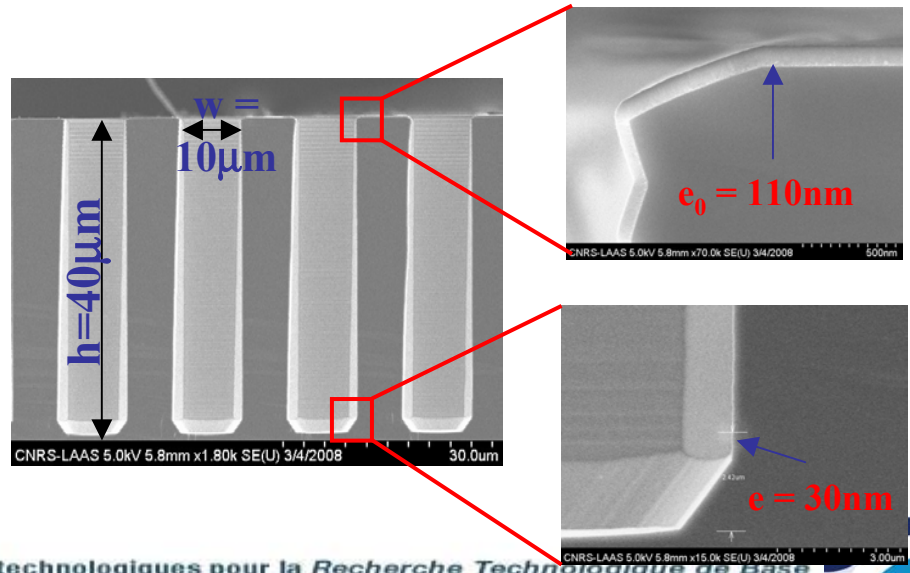
SiO_2 (5 nm) / Si_3N_4 (20 nm) $\epsilon_r = 3.9 / 7$ In-situ boron doped polySi 1.5 m Ω .cm



-60 nF/mm²
-f_{max} = 1MHz

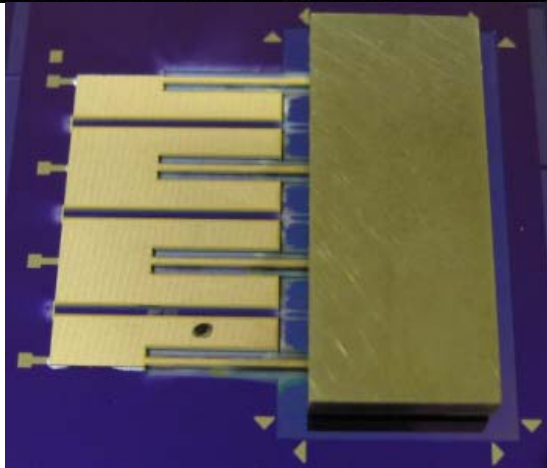
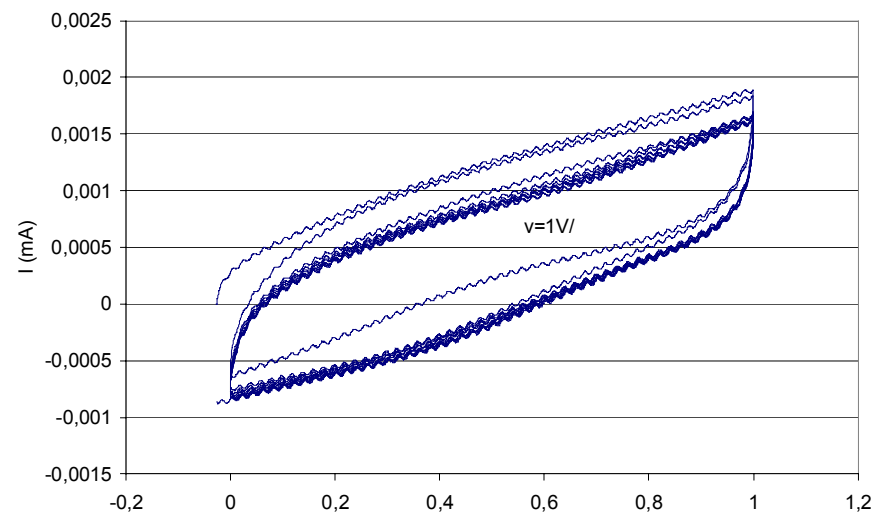
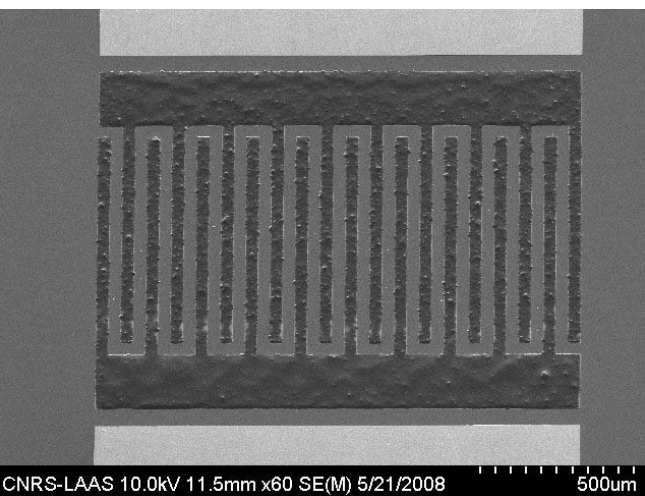
• ZrO₂ MOCVD deposition

- $\epsilon_r = 20-40$

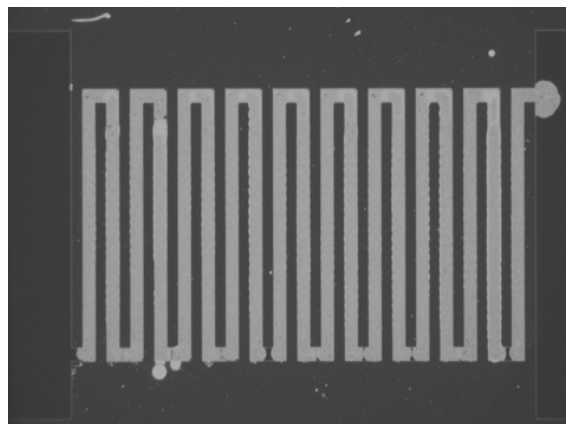


Energy Harvesting, storage, protection

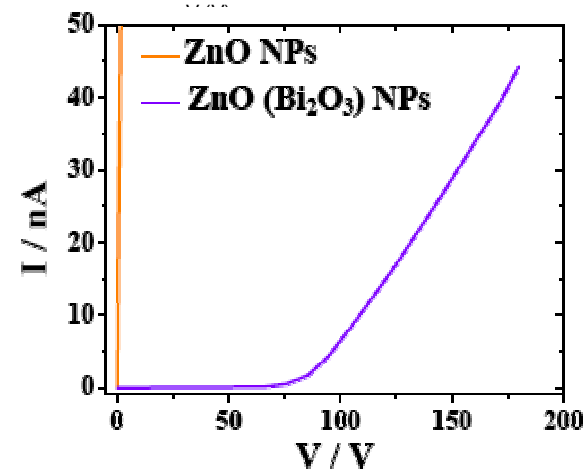
Supercapacitors: inkjet deposition



MEMS harvesting

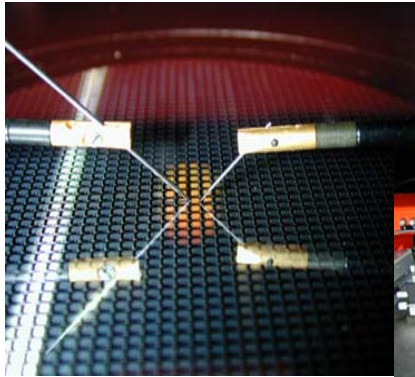


Zno Varistance

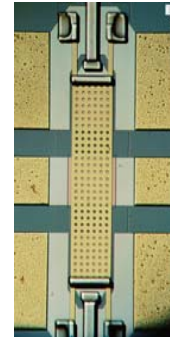
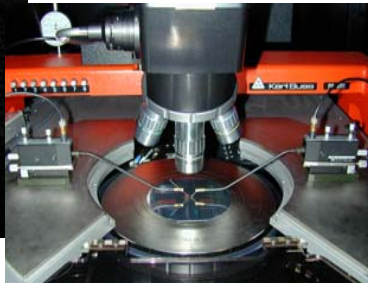


Characterization facilities

☞ Tests and characterizations of materials, components and systems:

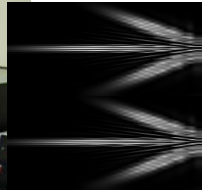
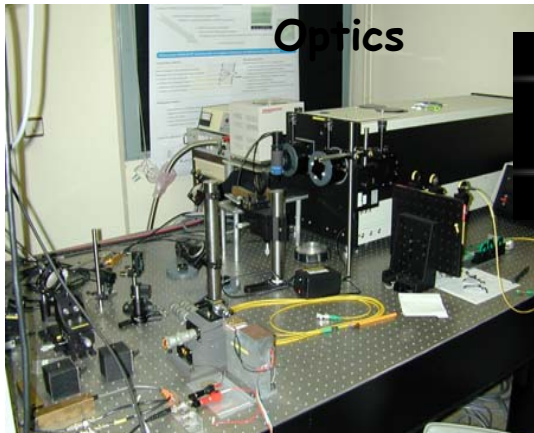


▪ **Electronics**

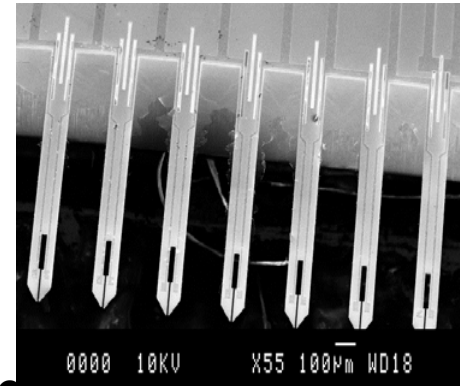
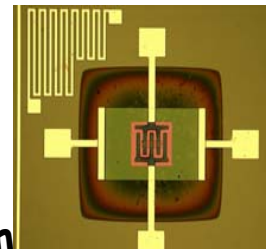


▪ **Ultra High Frequency**

▪ **Optics**



▪ **Micro & Nano Systems**



- Surface : 500m
- 55 test benches
- 5 engineers and technicians
- Annual operational budget ~80k€